



# THE DATASHEET OF STTH30L06D



## Turbo 2 ultrafast high voltage rectifier

### Main product characteristics

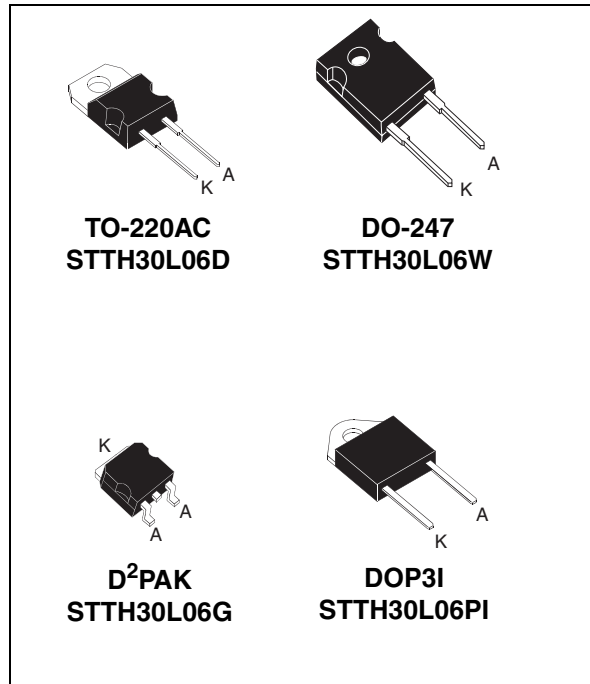
$I_{F(AV)}$	30 A
$V_{RRM}$	600 V
$T_j$	175°C
$V_F$ (typ)	1.0 V
$t_{rr}$ (max)	65 ns

### Features and benefits

- Ultrafast switching
- Low reverse current
- Low thermal resistance
- Reduces switching & conduction losses
- Package insulation voltage  
DOP3I: 2500 V<sub>RMS</sub>

### Description

The STTH30L06, which is using ST Turbo 2 600V technology, is specially suited for use in switching power supplies, and industrial applications, as rectification and discontinuous mode PFC boost diode.



### Order codes

Part Number	Marking
STTH30L06D	STTH30L06D
STTH30L06G	STTH30L06G
STTH30L06G-TR	STTH30L06G
STTH30L06W	STTH30L06W
STTH30L06PI	STTH30L06PI

# 1 Characteristics

**Table 1. Absolute ratings (limiting values)**

Symbol	Parameter		Value	Unit	
$V_{RRM}$	Repetitive peak reverse voltage		600	V	
$I_{F(RMS)}$	RMS forward voltage		50	A	
$I_{F(AV)}$	Average forward current	TO-220AC / TO-247 / D <sup>2</sup> PAK	$T_c = 125^\circ\text{C}$ $\delta = 0.5$	30	A
		DOP3I	$T_c = 95^\circ\text{C}$ $\delta = 0.5$		
$I_{FSM}$	Surge non repetitive forward current		$t_p = 10\text{ ms}$ sinusoidal	160	A
$T_{stg}$	Storage temperature range		-65 to + 175	°C	
$T_j$	Maximum operating junction temperature		175	°C	

**Table 2. Thermal resistance**

Symbol	Parameter		Value (max.)	Unit
$R_{th(j-c)}$	Junction to case	TO-220AC / TO-247 / D <sup>2</sup> PAK	1.1	°C/W
		DOP3I	1.7	

**Table 3. Static electrical characteristics**

Symbol	Parameter	Test conditions		Min.	Typ	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25^\circ\text{C}$	$V_R = V_{RRM}$			25	$\mu\text{A}$
		$T_j = 150^\circ\text{C}$			80	800	
$V_F^{(2)}$	Forward voltage drop	$T_j = 25^\circ\text{C}$	$I_F = 30\text{ A}$			1.55	V
		$T_j = 150^\circ\text{C}$			1.0	1.25	

1. Pulse test:  $t_p = 5\text{ ms}$ ,  $\delta < 2\%$

2. Pulse test:  $t_p = 380\text{ }\mu\text{s}$ ,  $\delta < 2\%$

To evaluate the conduction losses use the following equation:  $P = 0.95 \times I_{F(AV)} + 0.010 I_{F(RMS)}^2$

**Table 4. Dynamic Characteristics**

Symbol	Parameter	Test conditions		Min	Typ	Max	Unit
$t_{rr}$	Reverse recovery time	$T_j = 25^\circ\text{C}$	$I_F = 0.5\text{ A}$ $I_{rr} = 0.25\text{ A}$ $I_R = 1\text{ A}$			65	ns
			$I_F = 1\text{ A}$ $di_F/dt = 50\text{ A}/\mu\text{s}$ $V_R = 30\text{ V}$		65	90	
$I_{RM}$	Reverse recovery current	$T_j = 125^\circ\text{C}$	$I_F = 30\text{ A}$ $V_R = 400\text{ V}$ $di_F/dt = 100\text{ A}/\mu\text{s}$		11.5	16	A
$t_{fr}$	Forward recovery time	$T_j = 25^\circ\text{C}$	$I_F = 30\text{ A}$ $di_F/dt = 100\text{ A}/\mu\text{s}$ $V_{FR} = 1.1 \times V_{Fmax}$			500	ns
$V_{FP}$	Forward recovery voltage	$T_j = 25^\circ\text{C}$	$I_F = 30\text{ A}$ $di_F/dt = 100\text{ A}/\mu\text{s}$ $V_{FR} = 1.1 \times V_{Fmax}$		2.5		V

Figure 1. Conduction losses versus average forward current

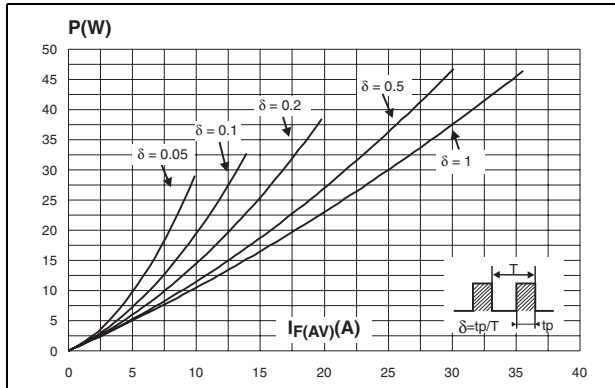


Figure 2. Forward voltage drop versus forward current

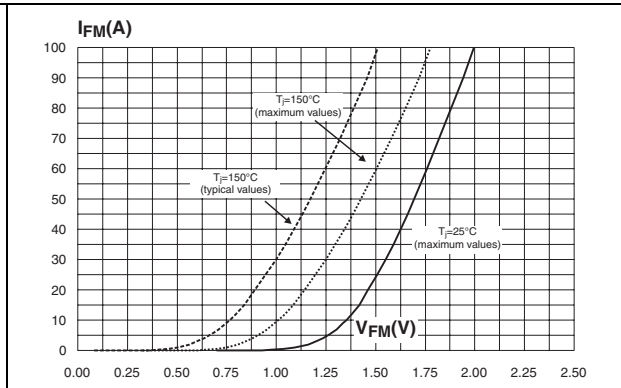


Figure 3. Relative variation of thermal impedance junction to case versus pulse duration

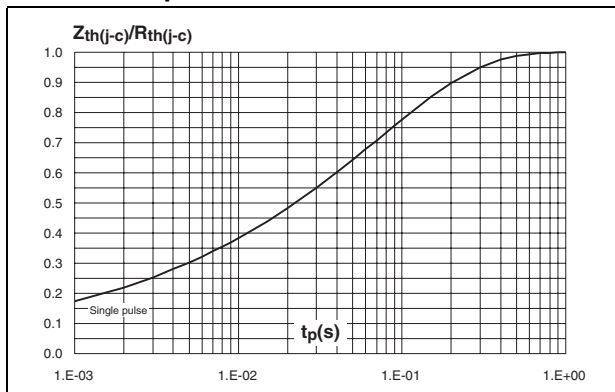


Figure 4. Peak reverse recovery current versus di\_F/dt (typical values)

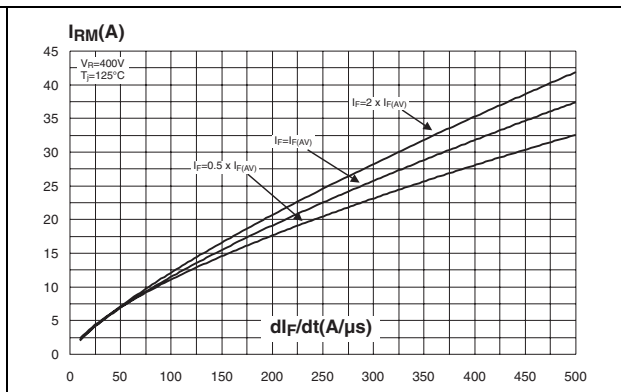


Figure 5. Reverse recovery time versus di\_F/dt (typical values)

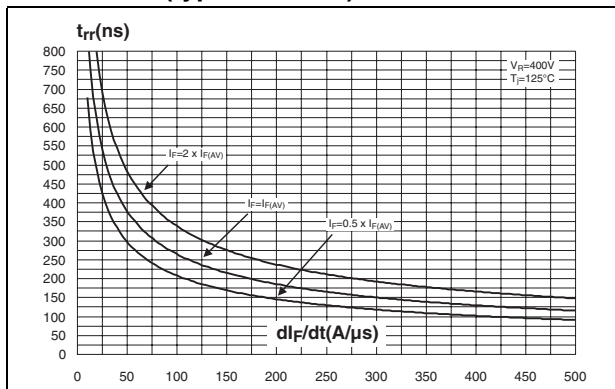


Figure 6. Reverse recovery charges versus di\_F/dt (typical values)

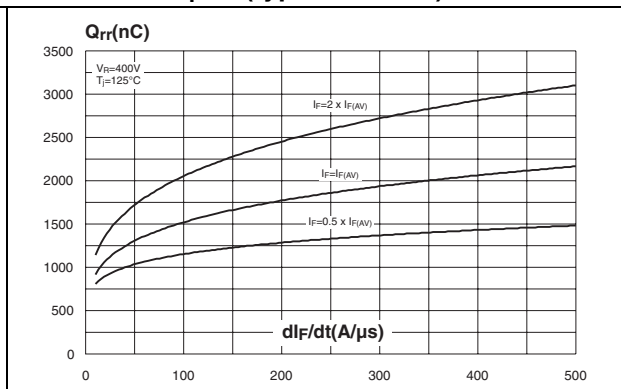


Figure 7. Reverse recovery softness factor versus  $di_F/dt$  (typical values)

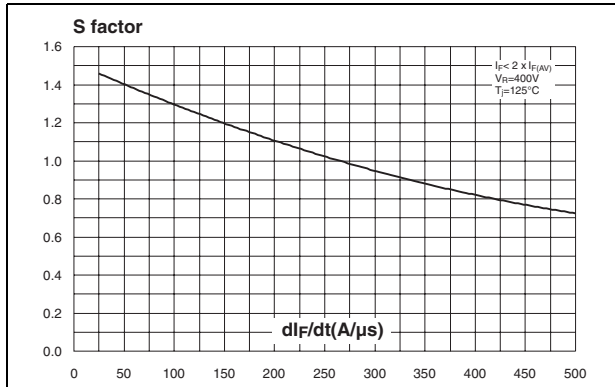


Figure 8. Relative variations of dynamic parameters versus junction temperature

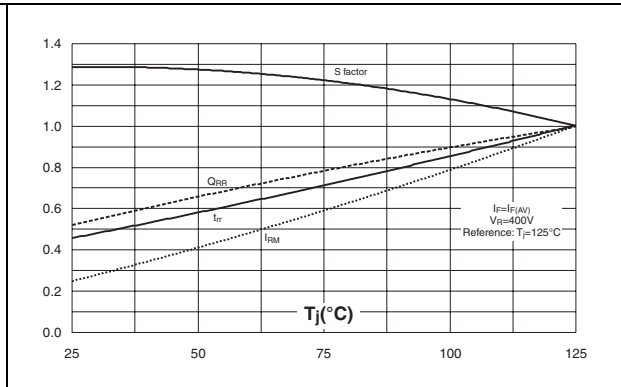


Figure 9. Transient peak forward voltage versus  $di_F/dt$  (typical values)

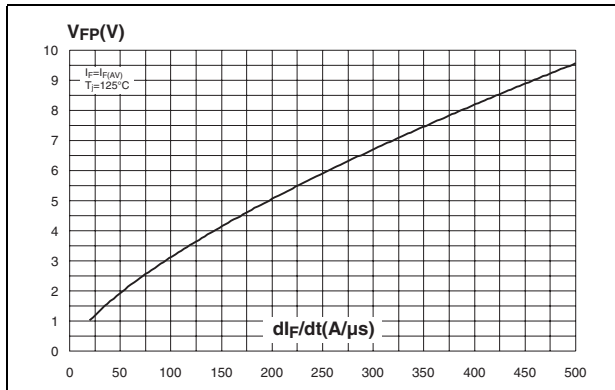


Figure 10. Forward recovery time versus  $di_F/dt$  (typical values)

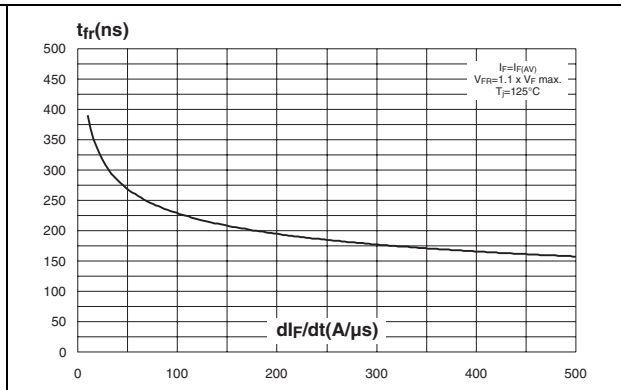


Figure 11. Junction capacitance versus reverse voltage applied (typical values)

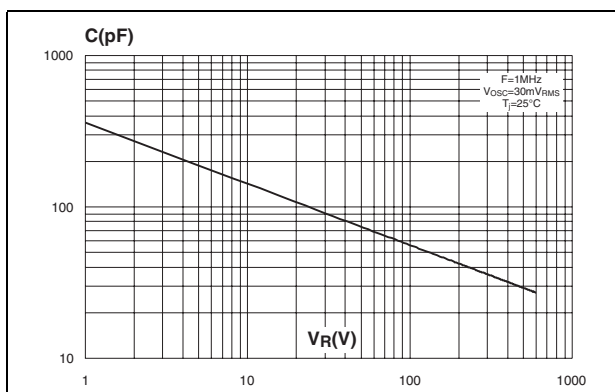
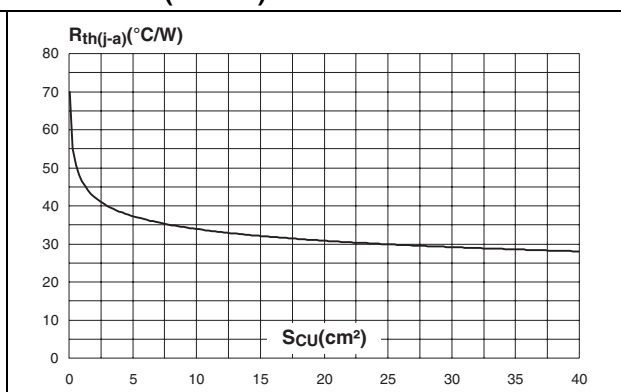


Figure 12. Thermal resistance junction to ambient versus copper surface under tab (epoxy FR4,  $e_{CU}=35\mu m$ ) ( $D^2PAK$ )



## 2 Package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.8 Nm (TO-220FPAC) / 0.55 Nm (TO-220AC)
- Maximum torque value: 1.0 Nm (TO-220FPAC) / 0.70 Nm (TO-220AC)

Table 5. D<sup>2</sup>PAK dimensions

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
A1	2.49	2.69	0.098	0.106
A2	0.03	0.23	0.001	0.009
B	0.70	0.93	0.027	0.037
B2	1.14	1.70	0.045	0.067
C	0.45	0.60	0.017	0.024
C2	1.23	1.36	0.048	0.054
D	8.95	9.35	0.352	0.368
E	10.00	10.40	0.393	0.409
G	4.88	5.28	0.192	0.208
L	15.00	15.85	0.590	0.624
L2	1.27	1.40	0.050	0.055
L3	1.40	1.75	0.055	0.069
M	2.40	3.20	0.094	0.126
R	0.40 typ.		0.016 typ.	
V2	0°	8°	0°	8°

Figure 13. D<sup>2</sup>PAK footprint (dimensions in mm)

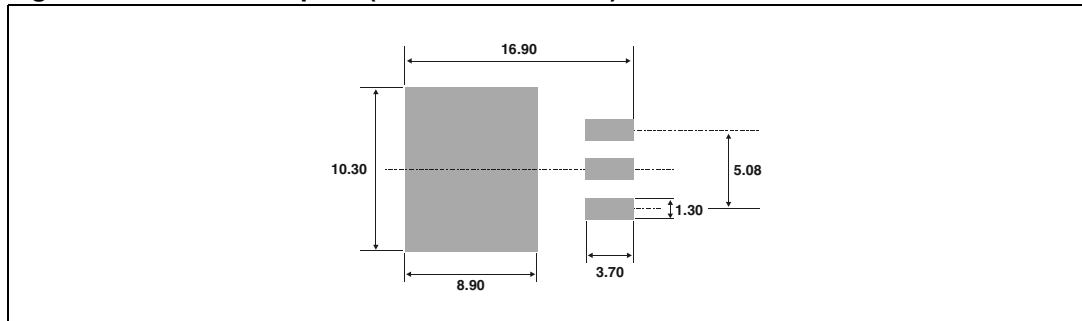
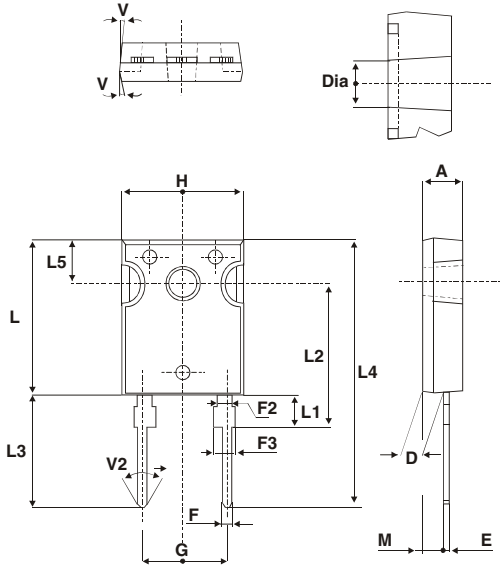


Table 6. DO247 dimensions



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.85		5.15	0.191		0.203
D	2.20		2.60	0.086		0.102
E	0.40		0.80	0.015		0.031
F	1.00		1.40	0.039		0.055
F2		2.00			0.078	
F3	2.00		2.40	0.078		0.094
G		10.90			0.429	
H	15.45		15.75	0.608		0.620
L	19.85		20.15	0.781		0.793
L1	3.70		4.30	0.145		0.169
L2		18.50			0.728	
L3	14.20		14.80	0.559		0.582
L4		34.60			1.362	
L5		5.50			0.216	
M	2.00		3.00	0.078		0.118
V		5°			5°	
V2		60°			60°	
Dia.	3.55		3.65	0.139		0.143



Table 8. DOP3I dimensions

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
b	1.20	1.40	0.047	0.055
c	1.45	1.55	0.057	0.061
c1	0.50	0.70	0.020	0.028
D	12.15	13.10	0.474	0.516
E	15.10	15.50	0.594	0.610
E1	7.55	7.75	0.297	0.305
e	10.80	11.30	0.425	0.445
G	20.4	21.10	0.815	0.831
L	14.35	15.60	0.565	0.614
P	4.08	4.17	0.161	0.164
Q	2.70	2.90	0.106	0.114
R	4.60 typ.		0.181 typ.	
Y	15.80	16.50	0.622	0.650

### 3 Ordering information

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STTH30L06D	STTH30L06D	TO-220AC	1.90 g	50	Tube
STTH30L06G	STTH30L06G	D <sup>2</sup> PAK	1.48 g	50	Tube
STTH30L06G-TR	STTH30L06G	D <sup>2</sup> PAK	1.48 g	1000	Tape & reel
STTH30L06W	STTH30L06W	DO-247	4.40 g	30	Tube
STTH30L06PI	STTH30L06PI	DOP3I	4.46 g	30	Tube

### 4 Revision history

Date	Revision	Changes
07-Sep-2004	1	First issue.
21-Oct-2004	2	DOP3I package added.
11-Jan-06	3	On page 2: <ul style="list-style-type: none"> <li>– I<sub>F(RMS)</sub> corrected from 30 A to 50 A</li> <li>– I<sub>F(AV)</sub> corrected from 50 A to 30 A</li> </ul>
10-Aug-2006	4	Reformatted to current standards. SOD-93 package removed.

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